

PSMN1R9-40YSB-VB Datasheet

N-Channel 40-V (D-S) MOSFET

PRODUCT SUMMARY

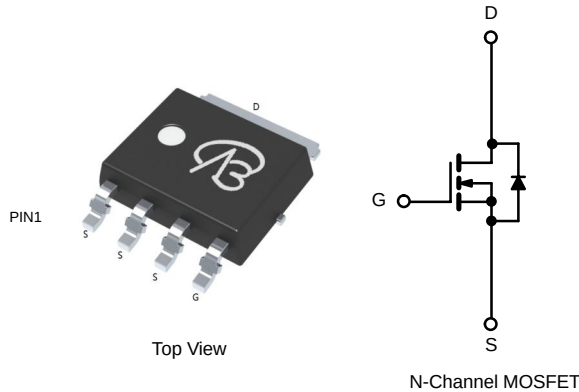
V_{DS} (V)	$R_{DS(on)}$ (Ω)	I_D (A) ^{a, c}	Q_g (Typ.)
40	0.0007 at $V_{GS} = 10$ V	150	80 nC
	0.0008 at $V_{GS} = 7.5$ V	120	

FEATURES

- SGT Power MOSFET
- 100 % R_g and UIS Tested

APPLICATIONS

- Synchronous Rectification
- Power Supplies


RoHS
 COMPLIANT


ABSOLUTE MAXIMUM RATINGS $T_A = 25^\circ\text{C}$, unless otherwise noted

Parameter		Symbol	Limit	Unit
Drain-Source Voltage		V_{DS}	40	V
Gate-Source Voltage		V_{GS}	± 25	
Continuous Drain Current ($T_J = 175^\circ\text{C}$)	$T_C = 25^\circ\text{C}$	I_D	150 ^{a, c}	A
	$T_C = 70^\circ\text{C}$		96 ^c	
	$T_A = 25^\circ\text{C}$		29 ^b	
	$T_A = 70^\circ\text{C}$		23 ^b	
Pulsed Drain Current		I_{DM}	450	
Avalanche Current Pulse		I_{AS}	80	
Single Pulse Avalanche Energy		E_{AS}	320	mJ
Continuous Source-Drain Diode Current	$T_C = 25^\circ\text{C}$	I_S	120 ^{a, c}	A
	$T_A = 25^\circ\text{C}$		2.6 ^b	
Maximum Power Dissipation	$T_C = 25^\circ\text{C}$	P_D	375 ^a	W
	$T_C = 70^\circ\text{C}$		263	
	$T_A = 25^\circ\text{C}$		3.75 ^b	
	$T_A = 70^\circ\text{C}$		2.6 ^b	
Operating Junction and Storage Temperature Range		T_J, T_{stg}	- 55 to 175	$^\circ\text{C}$

THERMAL RESISTANCE RATINGS

Parameter		Symbol	Typical	Maximum	Unit
Maximum Junction-to-Ambient ^b	Steady State	R_{thJA}	32	40	$^\circ\text{C/W}$
	Steady State	R_{thJC}	0.33	0.4	

Notes:

a. Based on $T_C = 25^\circ\text{C}$.

b. Surface Mounted on 1" x 1" FR4 board.

c. Calculated based on maximum junction temperature. Package limitation current is 150 A.

SPECIFICATIONS $T_J = 25\text{ }^{\circ}\text{C}$, unless otherwise noted						
Parameter	Symbol	Test Conditions	Min.	Typ.	Max.	Unit
Static						
Drain-Source Breakdown Voltage	V_{DS}	$V_{GS} = 0\text{ V}, I_D = 250\text{ }\mu\text{A}$	40			V
V_{DS} Temperature Coefficient	$\Delta V_{DS}/T_J$	$I_D = 250\text{ }\mu\text{A}$		41		mV/ $^{\circ}\text{C}$
$V_{GS(th)}$ Temperature Coefficient	$\Delta V_{GS(th)}/T_J$			- 8		
Gate-Source Threshold Voltage	$V_{GS(th)}$	$V_{DS} = V_{GS}, I_D = 250\text{ }\mu\text{A}$	2		4	V
Gate-Source Leakage	I_{GSS}	$V_{DS} = 0\text{ V}, V_{GS} = \pm 20\text{ V}$			± 100	nA
Zero Gate Voltage Drain Current	I_{DSS}	$V_{DS} = 40\text{ V}, V_{GS} = 0\text{ V}$			1	μA
		$V_{DS} = 40\text{ V}, V_{GS} = 0\text{ V}, T_J = 55\text{ }^{\circ}\text{C}$			10	
On-State Drain Current ^a	$I_{D(on)}$	$V_{DS} \geq 5\text{ V}, V_{GS} = 10\text{ V}$	150			A
Drain-Source On-State Resistance ^a	$R_{DS(on)}$	$V_{GS} = 10\text{ V}, I_D = 30\text{ A}$		0.0007		Ω
		$V_{GS} = 7.5\text{ V}, I_D = 20\text{ A}$		0.0008		
Forward Transconductance ^a	g_{fs}	$V_{DS} = 15\text{ V}, I_D = 30\text{ A}$		100		S
Dynamic ^b						
Input Capacitance	C_{iss}	$V_{DS} = 20\text{ V}, V_{GS} = 0\text{ V}, f = 1\text{ MHz}$		6000		pF
Output Capacitance	C_{oss}			1650		
Reverse Transfer Capacitance	C_{rss}			450		
Total Gate Charge	Q_g	$V_{DS} = 20\text{ V}, V_{GS} = 10\text{ V}, I_D = 20\text{ A}$		80	100	nC
Gate-Source Charge	Q_{gs}			30		
Gate-Drain Charge	Q_{gd}			16		
Gate Resistance	R_g	$f = 1\text{ MHz}$		0.85	1.3	Ω
Turn-On Delay Time	$t_{d(on)}$	$V_{DD} = 20\text{ V}, R_L = 1.0\text{ }\Omega$ $I_D \cong 20\text{ A}, V_{GEN} = 10\text{ V}, R_g = 1\text{ }\Omega$		20	30	ns
Rise Time	t_r			11	17	
Turn-Off Delay Time	$t_{d(off)}$			77	115	
Fall Time	t_f			10	15	
Turn-On Delay Time	$t_{d(on)}$	$V_{DD} = 20\text{ V}, R_L = 1.0\text{ }\Omega$ $I_D \cong 20\text{ A}, V_{GEN} = 4.5\text{ V}, R_g = 1\text{ }\Omega$		20		
Rise Time	t_r			18		
Turn-Off Delay Time	$t_{d(off)}$			50		
Fall Time	t_f			30		
Drain-Source Body Diode Characteristics						
Continuous Source-Drain Diode Current	I_S	$T_C = 25\text{ }^{\circ}\text{C}$			120	A
Pulse Diode Forward Current ^a	I_{SM}				200	
Body Diode Voltage	V_{SD}	$I_S = 20\text{ A}$		0.8	1.2	V
Body Diode Reverse Recovery Time	t_{rr}	$I_F = 20\text{ A}, di/dt = 100\text{ A}/\mu\text{s}, T_J = 25\text{ }^{\circ}\text{C}$		50		ns
Body Diode Reverse Recovery Charge	Q_{rr}			40	65	nC
Reverse Recovery Fall Time	t_a			20		ns
Reverse Recovery Rise Time	t_b			17		

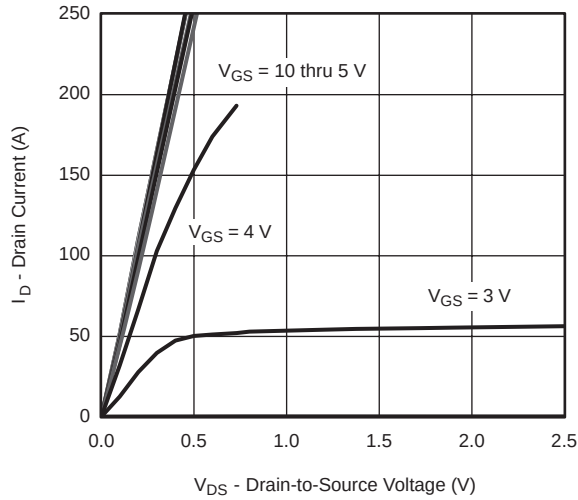
Notes:

a. Pulse test; pulse width $\leq 300\text{ }\mu\text{s}$, duty cycle $\leq 2\%$.

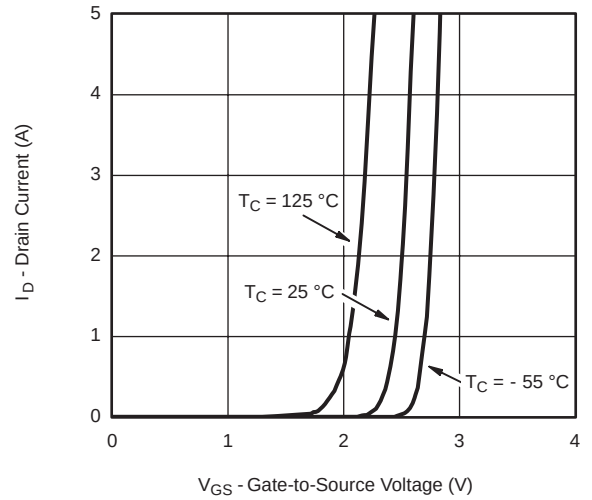
b. Guaranteed by design, not subject to production testing.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

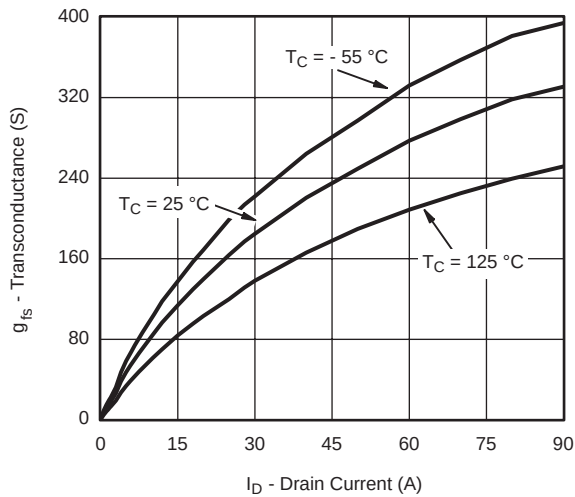
TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



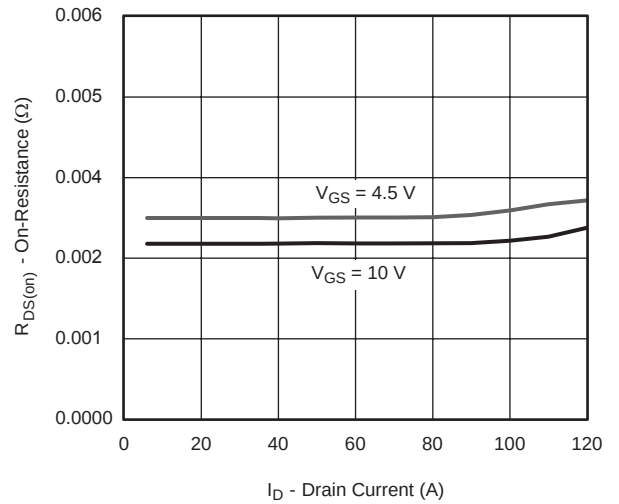
Output Characteristics



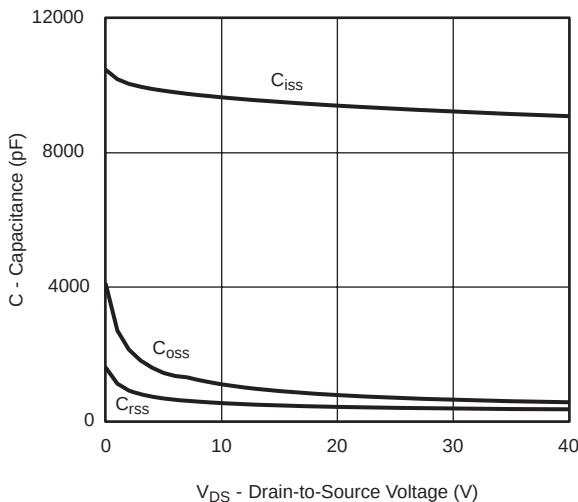
Transfer Characteristics



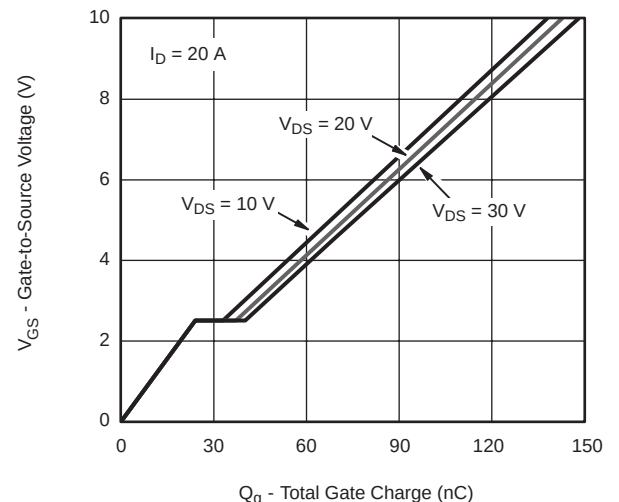
Transconductance



On-Resistance vs. Drain Current

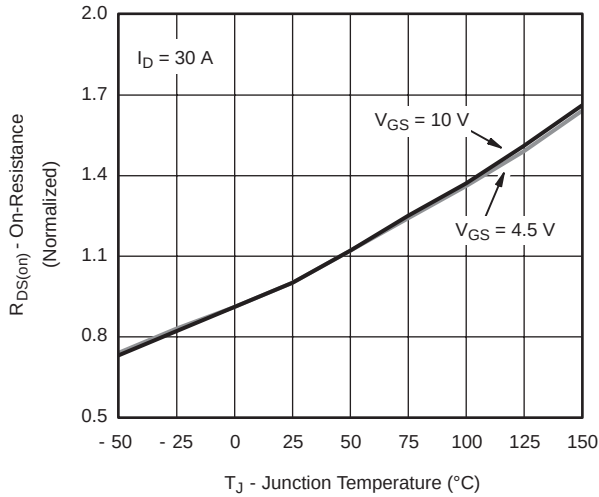


Capacitance

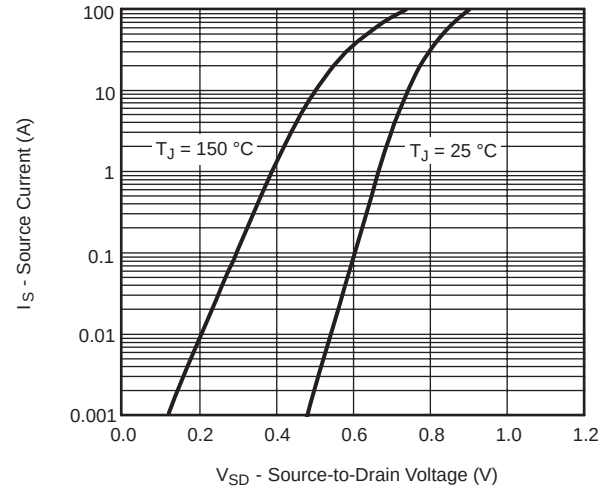


Gate Charge

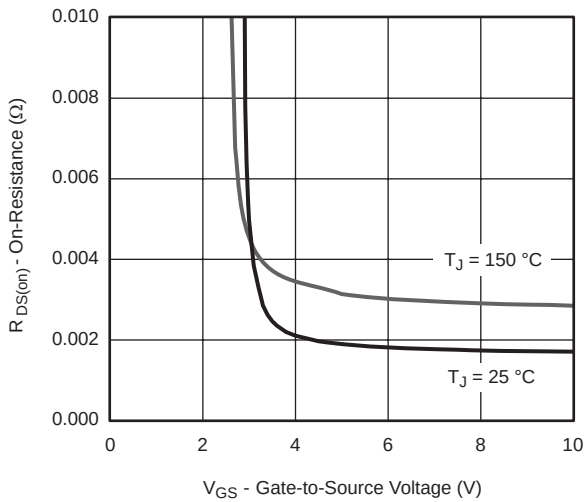
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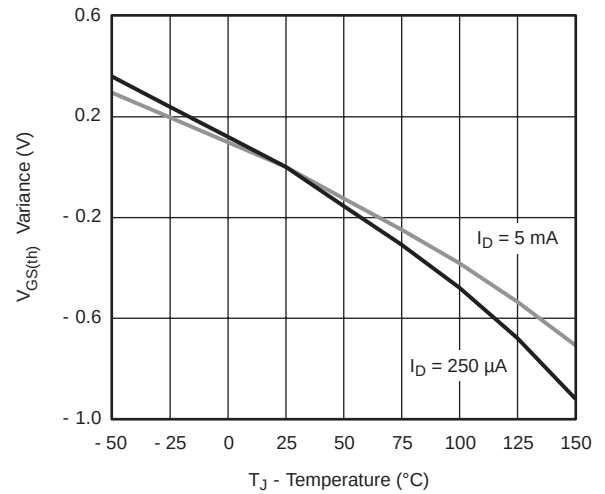
On-Resistance vs. Junction Temperature



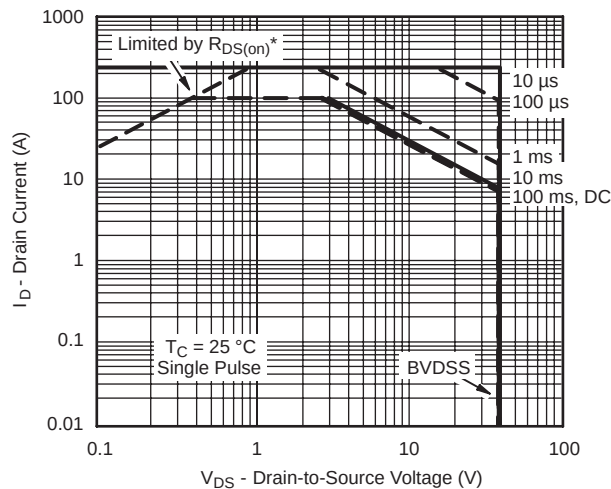
Forward Diode Voltage vs. Temperature



On-Resistance vs. Gate-to-Source Voltage



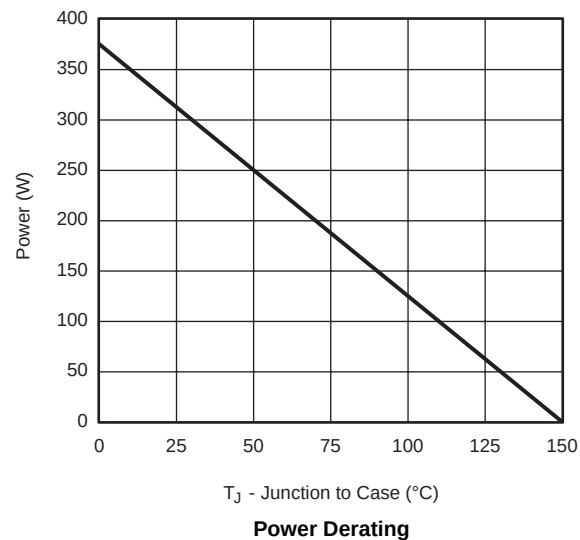
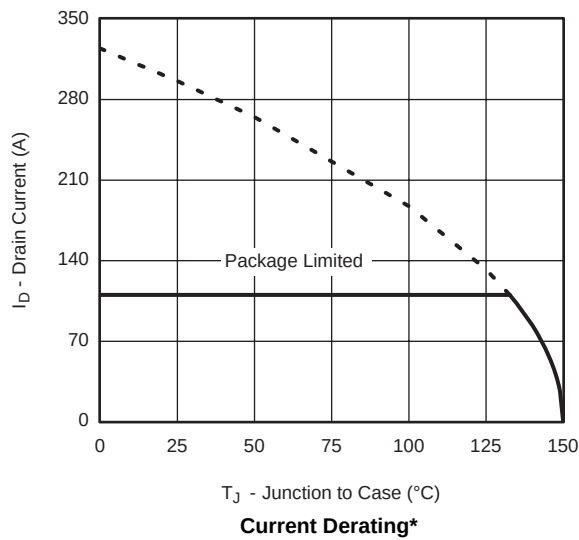
Threshold Voltage



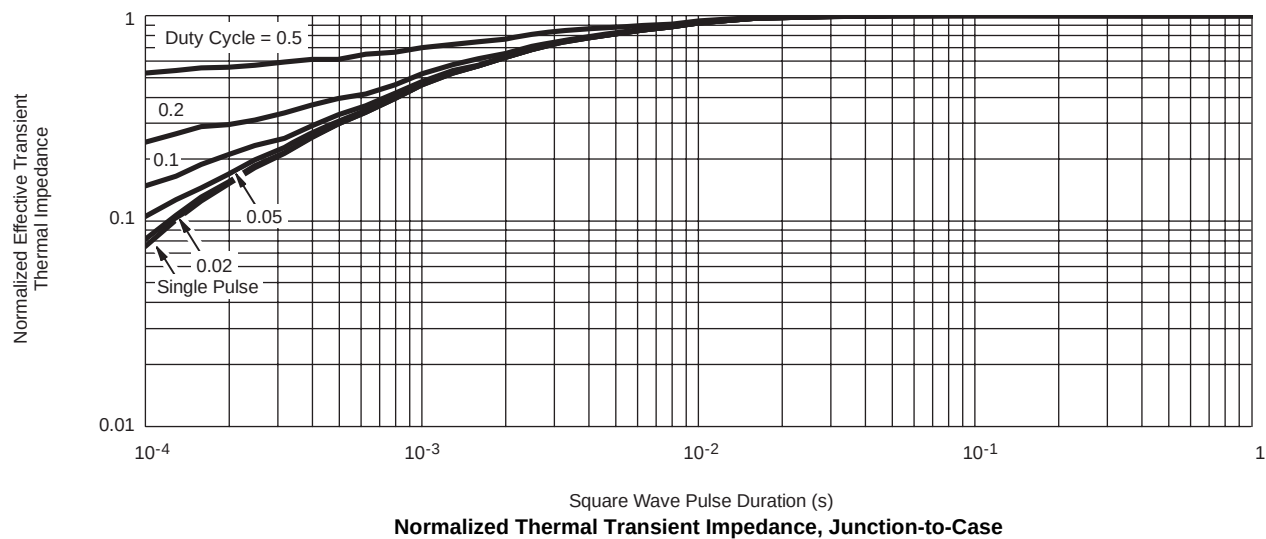
* $V_{GS} >$ minimum V_{GS} at which $R_{DS(on)}$ is specified

Safe Operating Area, Junction-to-Ambient

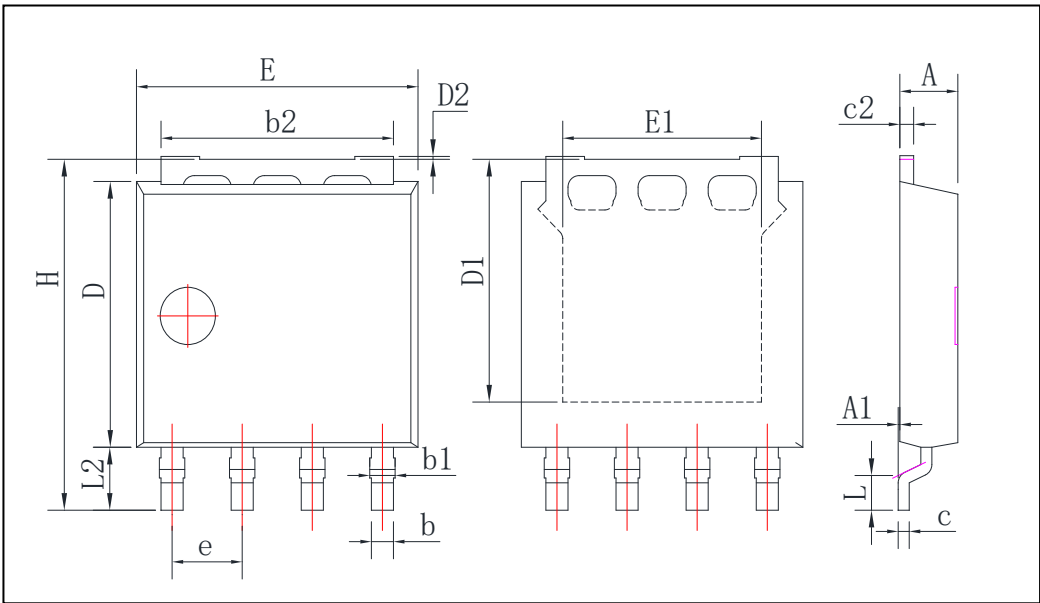
TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



* The power dissipation P_D is based on $T_{J(max)} = 150\text{ °C}$, using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package limit.



LFPK56 CASE OUTLINE



Symbol	Min	Typ	Max
A	1.00	1.05	1.10
A1	0.00		0.15
b	0.35	0.40	0.50
b1	0.40	0.48	0.58
b2	4.01	4.21	4.41
c	0.18	0.20	0.25
c2	0.23	0.25	0.30
D	4.44	4.59	4.70
D1	4.10	4.24	4.40
D2			0.20
e	1.22	1.27	1.32
E	5.00	5.10	5.25
E1	3.50	3.60	3.70
H	6.05	6.15	6.25
L	0.40	0.60	0.80
L2	0.90	1.10	1.30

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